

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RU-SHANG HSIAO	03/08/2014
LING-SUNG WANG	03/11/2014
CHIH-MU HUANG	03/10/2014
CHIH-KANG CHAO	03/10/2014
CHEN-CHIEH CHIANG	03/10/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN ROAD 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15004365
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NAME OF SUBMITTER:	LADONNA JOHNSON
SIGNATURE:	/LaDonna Johnson/
DATE SIGNED:	01/22/2016

Total Attachments: 3

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Docket No.: 2013-1557/24061.2757

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Ru-Shang Hsiao of No. 9, Lane 29, Zihciang S. Road
Jhubei City, Hsinchu County 302
Taiwan, R.O.C.
- (2) Ling-Sung Wang of No. 3, Alley 117, Lane 851, Section 2
Zhonghua W. Road, West Central District
Tainan City 70063, Taiwan, R.O.C.
- (3) Chih-Mu Huang of No. 213, Xiwei, Shanhua District
Tainan City 741, Taiwan, R.O.C.
- (4) Chih-Kang Chao of No. 15, Lane 163, Yuxiao Road, East District
Tainan City 701, Taiwan, R.O.C.
- (5) Chen-Chieh Chiang of 18F.-2, No. 357, Dazhong 2nd Road
Zuoying District, Kaohsiung City 81369
Taiwan, R.O.C.

have invented certain improvements in

STRUCTURE AND METHOD FOR SEMICONDUCTOR DEVICE

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on and assigned application number ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any

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official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ru-Shang Hsiao

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Taiwan, R.O.C.

Dated: 2014.03.08

Ru Shang Hsiao
Inventor Signature

Inventor Name: Ling-Sung Wang

Residence Address: No. 3, Alley 117, Lane 851, Section 2, Zhonghua W. Road
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Dated: 2014.3.11

Ling Sung Wang
Inventor Signature

Inventor Name: Chih-Mu Huang

Residence Address: No. 213, Xiwei, Shanhu District, Tainan City 741, Taiwan, R.O.C.

Dated: 2014.3.10

Chih-Mu Huang
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Dated: 3/6

Chih-Kang Chao
Inventor Signature

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Residence Address: 18F.-2, No. 357, Dazhong 2nd Road, Zuoying District
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Dated: 3/10. 2014

Chen-Chieh Chiang
Inventor Signature